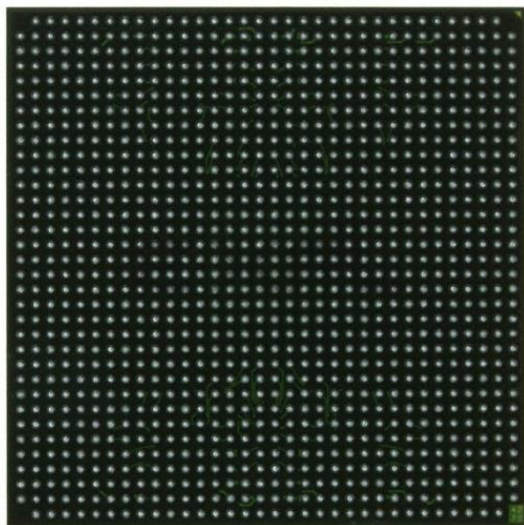




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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	5760
Number of Logic Elements/Cells	-
Total RAM Bits	2211840
Number of I/O	824
Number of Gates	4000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v4000-6ffg1152c

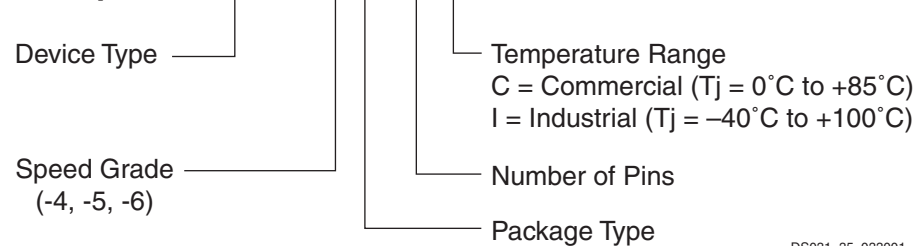
Table 6: Virtex-II Device/Package Combinations and Maximum Number of Available I/Os (Advance Information)

Package ^(1,2)	Available I/Os										
	XC2V 40	XC2V 80	XC2V 250	XC2V 500	XC2V 1000	XC2V 1500	XC2V 2000	XC2V 3000	XC2V 4000	XC2V 6000	XC2V 8000
CS144/CSG144	88	92	92	-	-	-	-	-	-	-	-
FG256/FGG256	88	120	172	172	172	-	-	-	-	-	-
FG456/FGG456	-	-	200	264	324	-	-	-	-	-	-
FG676/FGG676	-	-	-	-	-	392	456	484	-	-	-
FF896	-	-	-	-	432	528	624	-	-	-	-
FF1152	-	-	-	-	-	-	-	720	824	824	824
FF1517	-	-	-	-	-	-	-	-	912	1,104	1,108
BG575/BGG575	-	-	-	-	328	392	408	-	-	-	-
BG728/BGG728	-	-	-	-	-	-	-	516	-	-	-
BF957	-	-	-	-	-	-	624	684	684	684	-

Notes:

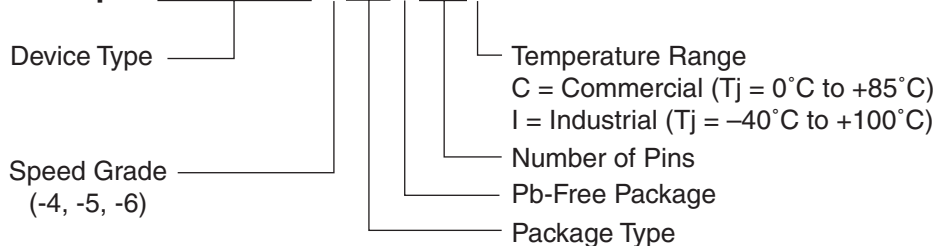
1. All devices in a particular package are pinout (footprint) compatible. In addition, the FG456/FGG456 and FG676/FGG676 packages are compatible, as are the FF896 and FF1152 packages.
2. Wire-bond packages CS144, FG256, FG456, FG676, BG575, and BG728 are also available in Pb-free versions CSG144, FGG256, FGG456, FGG676, BGG575, and BGG728. See [Virtex-II Ordering Examples](#) for details on how to order.

Virtex-II Ordering Examples

Example: XC2V1000-5FG456C


DS031_35_033001

Figure 2: Virtex-II Ordering Example. Regular Package

Example: XC2V3000-6BGG728C


DS031_35a_061804

Figure 3: Virtex-II Ordering Example. Pb-Free Package

Table 8: SelectI/O-Ultra Differential Buffers With On-Chip Termination

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 11 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the [Virtex-II Platform FPGA User Guide](#).

	HSTL_I	HSTL_II	HSTL_III	HSTL_IV
Conventional				
DCI Transmit Conventional Receive				
Conventional Transmit DCI Receive				
DCI Transmit DCI Receive				
Bidirectional	N/A		N/A	
Reference Resistor	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$
Recommended $Z_0^{(1)}$	50 Ω	50 Ω	50 Ω	50 Ω

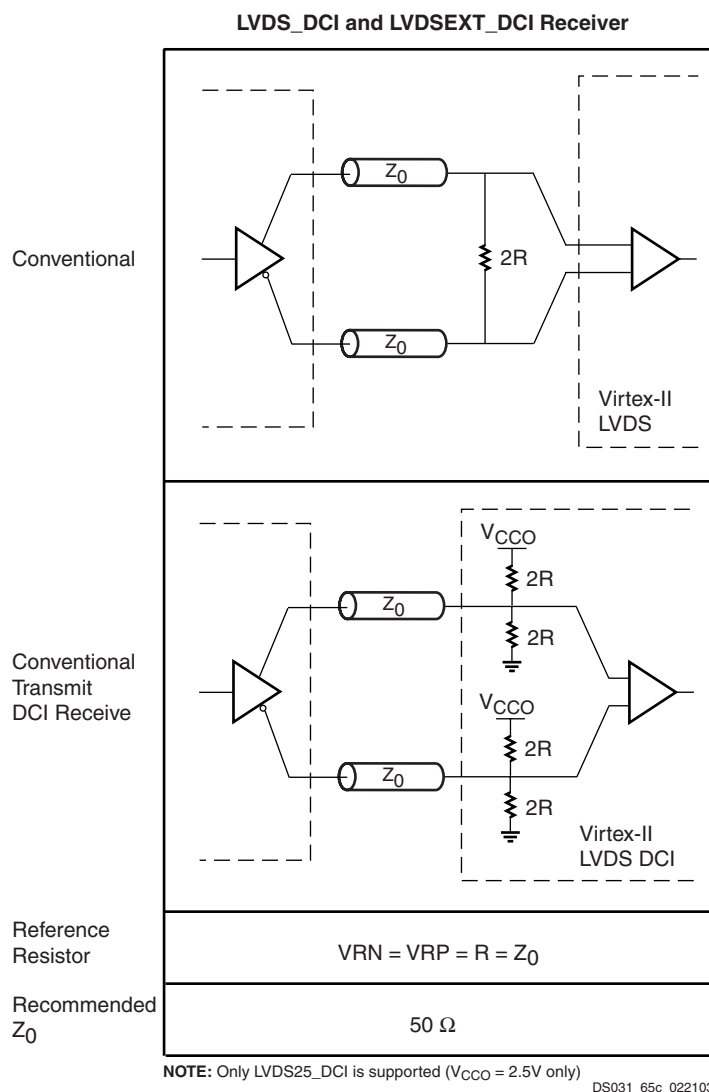
Note:

1. Z_0 is the recommended PCB trace impedance.

DS031_65a_100201

Figure 11: HSTL DCI Usage Examples

Figure 13 provides examples illustrating the use of the LVDS_DCI and LVDSEXT_DCI I/O standards. For a complete list, see the [Virtex-II Platform FPGA User Guide](#).



NOTE: Only LVDS25_DCI is supported ($V_{CCO} = 2.5V$ only)

DS031_65c_022103

Figure 13: LVDS DCI Usage Examples

Table 5: Minimum Power On Current Required for Virtex-II Devices

	Device (mA)							
	XC2V40, XC2V80, XC2V250, XC2V500	XC2V1000	XC2V1500	XC2V2000	XC2V3000	XC2V4000	XC2V6000	XC2V8000
$I_{CCINTMIN}$	200	250	350	400	500	650	800	1100
$I_{CCAUXMIN}$	100	100	100	100	100	100	100	100
I_{CCOMIN}	50	50	100	100	100	100	100	100

Notes:

1. Values specified for power on current parameters are Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.25.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note [XAPP623](#) for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Thus, V_{CCAUX} is especially susceptible to power supply noise.

Changes in V_{CCAUX} voltage outside of 200 mV peak to peak should take place at a rate no faster than 10 mV per millisecond. Techniques to help reduce jitter and period distortion are provided in Xilinx Answer Record 13756, available at [www.support.xilinx.com](#).

V_{CCAUX} can share a power plane with 3.3V V_{CCO} , but only if V_{CCO} does not have excessive noise. Using simultaneously switching output (SSO) limits are essential for keeping power supply noise to a minimum. Refer to [XAPP689](#), "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Table 6: DC Input and Output Levels

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL ⁽¹⁾	-0.5	0.8	2.0	3.6	0.4	2.4	24	-24
LVC MOS33	-0.5	0.8	2.0	3.6	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS25	-0.5	0.7	1.7	2.7	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS18	-0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	$V_{CCO} - 0.4$	16	-16
LVC MOS15	-0.5	35% V_{CCO}	65% V_{CCO}	1.7	0.4	$V_{CCO} - 0.4$	16	-16
PCI33_3	-0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
PCI66_3	-0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
PCI-X	-0.5	Note 2	Note 2	Note 2	Note 2	Note 2	Note 2	Note 2
GTLP	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.6	n/a	36	n/a
GTL	-0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	$V_{CCO} + 0.5$	0.4	n/a	40	n/a
HSTL I	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	8	-8
HSTL II	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	16	-16
HSTL III	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	24	-8
HSTL IV	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	48	-8

Enhanced Multiplier Switching Characteristics

Table 26 and Table 27 provide timing information for enhanced Virtex-II multiplier blocks, available in stepping revisions of Virtex-II devices. For more information on stepping revisions, availability, and ordering instructions, see your local sales representative.

Table 26: Enhanced Multiplier Switching Characteristics

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Propagation Delay to Output Pin					
Input to Pin 35	T _{MULT1_P35}	4.66	5.14	5.91	ns, Max
Input to Pin 34	T _{MULT1_P34}	4.57	5.03	5.79	ns, Max
Input to Pin 33	T _{MULT1_P33}	4.47	4.93	5.66	ns, Max
Input to Pin 32	T _{MULT1_P32}	4.37	4.82	5.54	ns, Max
Input to Pin 31	T _{MULT1_P31}	4.28	4.71	5.42	ns, Max
Input to Pin 30	T _{MULT1_P30}	4.18	4.61	5.29	ns, Max
Input to Pin 29	T _{MULT1_P29}	4.08	4.50	5.17	ns, Max
Input to Pin 28	T _{MULT1_P28}	3.99	4.39	5.05	ns, Max
Input to Pin 27	T _{MULT1_P27}	3.89	4.28	4.92	ns, Max
Input to Pin 26	T _{MULT1_P26}	3.79	4.18	4.80	ns, Max
Input to Pin 25	T _{MULT1_P25}	3.69	4.07	4.68	ns, Max
Input to Pin 24	T _{MULT1_P24}	3.60	3.96	4.56	ns, Max
Input to Pin 23	T _{MULT1_P23}	3.50	3.86	4.43	ns, Max
Input to Pin 22	T _{MULT1_P22}	3.40	3.75	4.31	ns, Max
Input to Pin 21	T _{MULT1_P21}	3.31	3.64	4.19	ns, Max
Input to Pin 20	T _{MULT1_P20}	3.21	3.54	4.06	ns, Max
Input to Pin 19	T _{MULT1_P19}	3.11	3.43	3.94	ns, Max
Input to Pin 18	T _{MULT1_P18}	3.02	3.32	3.82	ns, Max
Input to Pin 17	T _{MULT1_P17}	2.92	3.21	3.69	ns, Max
Input to Pin 16	T _{MULT1_P16}	2.82	3.11	3.57	ns, Max
Input to Pin 15	T _{MULT1_P15}	2.72	3.00	3.45	ns, Max
Input to Pin 14	T _{MULT1_P14}	2.63	2.89	3.33	ns, Max
Input to Pin 13	T _{MULT1_P13}	2.53	2.79	3.20	ns, Max
Input to Pin 12	T _{MULT1_P12}	2.43	2.68	3.08	ns, Max
Input to Pin 11	T _{MULT1_P11}	2.34	2.57	2.96	ns, Max
Input to Pin 10	T _{MULT1_P10}	2.24	2.47	2.83	ns, Max
Input to Pin 9	T _{MULT1_P9}	2.14	2.36	2.71	ns, Max
Input to Pin 8	T _{MULT1_P8}	2.05	2.25	2.59	ns, Max
Input to Pin 7	T _{MULT1_P7}	1.95	2.14	2.46	ns, Max
Input to Pin 6	T _{MULT1_P6}	1.85	2.04	2.34	ns, Max
Input to Pin 5	T _{MULT1_P5}	1.75	1.93	2.22	ns, Max
Input to Pin 4	T _{MULT1_P4}	1.66	1.82	2.10	ns, Max
Input to Pin 3	T _{MULT1_P3}	1.56	1.72	1.97	ns, Max
Input to Pin 2	T _{MULT1_P2}	1.46	1.61	1.85	ns, Max
Input to Pin 1	T _{MULT1_P1}	1.37	1.50	1.73	ns, Max
Input to Pin 0	T _{MULT1_P0}	1.27	1.40	1.60	ns, Max

CS144/CSG144 Chip-Scale BGA Package

As shown in [Table 5](#), XC2V40, XC2V80, and XC2V250 Virtex-II devices are available in the CS144/CSG144 package. Pins in the XC2V40, XC2V80, and XC2V250 devices are the same except for pin differences in the XC2V40 device, shown in the No Connect column. Following this table are the [CS144/CSG144 Chip-Scale BGA Package Specifications \(0.80mm pitch\)](#).

Table 5: CS144/CSG144 — XC2V40, XC2V80, and XC2V250

Bank	Pin Description	Pin Number	No Connect in the XC2V40
0	IO_L01N_0	B3	
0	IO_L01P_0	A3	
0	IO_L02N_0	C4	
0	IO_L02P_0	B4	
0	IO_L03N_0/VRP_0	A4	
0	IO_L03P_0/VRN_0	D5	
0	IO_L94N_0/VREF_0	A5	
0	IO_L94P_0	D6	
0	IO_L95N_0/GCLK7P	C6	
0	IO_L95P_0/GCLK6S	B6	
0	IO_L96N_0/GCLK5P	A6	
0	IO_L96P_0/GCLK4S	D7	
1	IO_L96N_1/GCLK3P	A7	
1	IO_L96P_1/GCLK2S	B7	
1	IO_L95N_1/GCLK1P	A8	
1	IO_L95P_1/GCLK0S	B8	
1	IO_L94N_1	C8	
1	IO_L94P_1/VREF_1	D8	
1	IO_L03N_1/VRP_1	C9	
1	IO_L03P_1/VRN_1	D9	
1	IO_L02N_1	A10	
1	IO_L02P_1	B10	
1	IO_L01N_1	C10	
1	IO_L01P_1	D10	
2	IO_L01N_2	C13	
2	IO_L01P_2	D11	
2	IO_L02N_2/VRP_2	D12	
2	IO_L02P_2/VRN_2	D13	
2	IO_L03N_2	E10	
2	IO_L03P_2/VREF_2	E11	
2	IO_L93N_2	E13	NC
2	IO_L93P_2/VREF_2	F11	NC
2	IO_L94N_2	F12	
2	IO_L94P_2	G10	

Table 5: CS144/CSG144 — XC2V40, XC2V80, and XC2V250

Bank	Pin Description	Pin Number	No Connect in the XC2V40
NA	CCLK	M13	
NA	PROG_B	B1	
NA	DONE	N12	
NA	M0	N2	
NA	M1	M2	
NA	M2	M3	
NA	TCK	B12	
NA	TDI	C1	
NA	TDO	C11	
NA	TMS	A13	
NA	PWRDWN_B	M12	
NA	HSWAP_EN	A1	
NA	RSVD	A2	
NA	RSVD	B2	
NA	VBATT	A12	
NA	RSVD	B11	
NA	VCCAUX	C2	
NA	VCCAUX	N1	
NA	VCCAUX	N13	
NA	VCCAUX	B13	
NA	VCCINT	H2	
NA	VCCINT	L7	
NA	VCCINT	H13	
NA	VCCINT	C7	
NA	GND	E1	
NA	GND	G2	
NA	GND	J1	
NA	GND	J4	
NA	GND	M5	
NA	GND	L9	
NA	GND	J11	
NA	GND	H10	
NA	GND	F13	
NA	GND	E12	
NA	GND	B9	
NA	GND	C5	

Notes:

- See Table 4 for an explanation of the signals available on this pin.

Table 6: FG256/FGG256 BGA — XC2V40, XC2V80, XC2V250, XC2V500, and XC2V1000

Bank	Pin Description	Pin Number	No Connect in XC2V40	No Connect in XC2V80
NA	GND	T16		
NA	GND	T1		
NA	GND	R15		
NA	GND	R2		
NA	GND	P14		
NA	GND	P3		
NA	GND	L11		
NA	GND	L6		
NA	GND	K10		
NA	GND	K9		
NA	GND	K8		
NA	GND	K7		
NA	GND	J10		
NA	GND	J9		
NA	GND	J8		
NA	GND	J7		
NA	GND	H10		
NA	GND	H9		
NA	GND	H8		
NA	GND	H7		
NA	GND	G10		
NA	GND	G9		
NA	GND	G8		
NA	GND	G7		
NA	GND	F11		
NA	GND	F6		
NA	GND	C14		
NA	GND	C3		
NA	GND	B15		
NA	GND	B2		
NA	GND	A16		
NA	GND	A1		

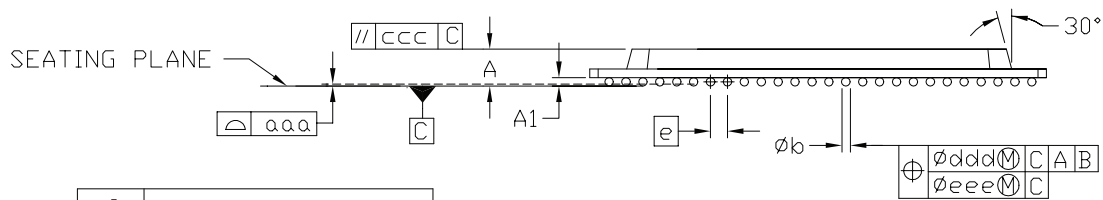
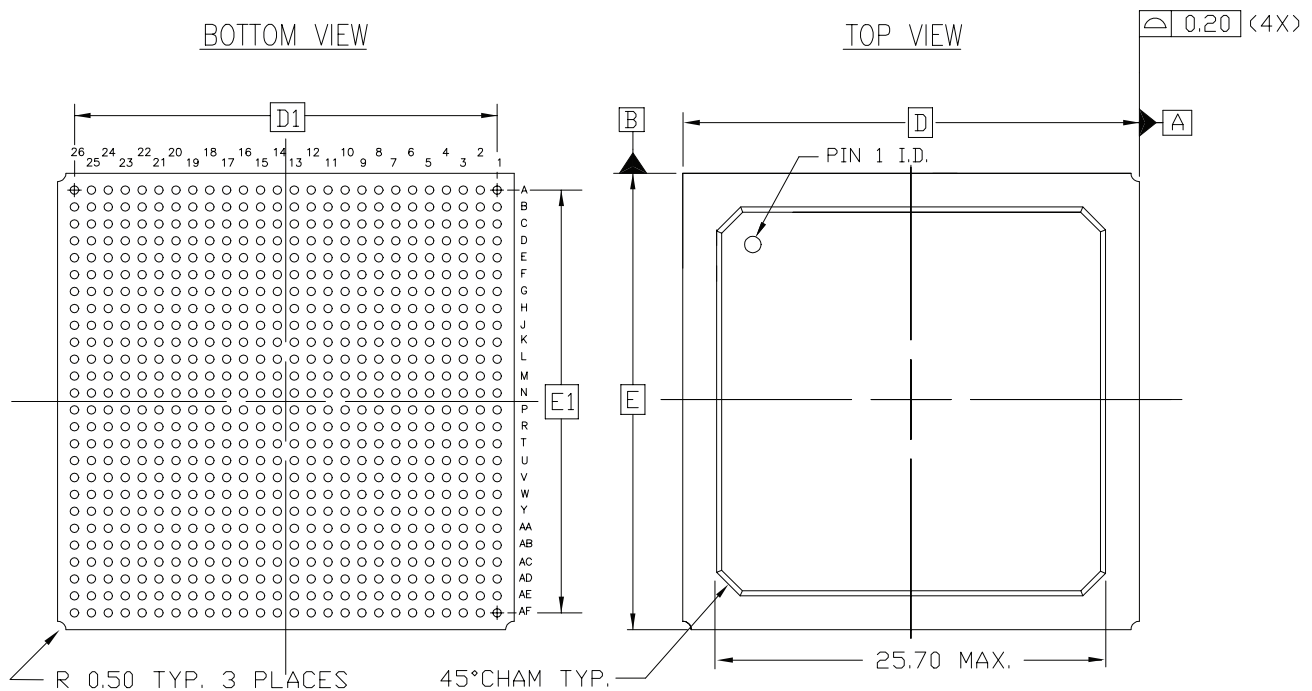
Notes:

- See Table 4 for an explanation of the signals available on this pin.

Table 8: FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
1	IO_L19N_1	E20		
1	IO_L19P_1	F20		
1	IO_L06N_1	B21		
1	IO_L06P_1	B22		
1	IO_L05N_1	A22		
1	IO_L05P_1	A23		
1	IO_L04N_1	C21		
1	IO_L04P_1/VREF_1	D21		
1	IO_L03N_1/VRP_1	C20		
1	IO_L03P_1/VRN_1	D20		
1	IO_L02N_1	A24		
1	IO_L02P_1	A25		
1	IO_L01N_1	B23		
1	IO_L01P_1	B24		
2	IO_L01N_2	B26		
2	IO_L01P_2	C26		
2	IO_L02N_2/VRP_2	G20		
2	IO_L02P_2/VRN_2	H20		
2	IO_L03N_2	C25		
2	IO_L03P_2/VREF_2	D25		
2	IO_L04N_2	E23		
2	IO_L04P_2	E24		
2	IO_L06N_2	G21		
2	IO_L06P_2	G22		
2	IO_L19N_2	D26		
2	IO_L19P_2	E26		
2	IO_L21N_2	F23		
2	IO_L21P_2/VREF_2	F24		
2	IO_L22N_2	E25		
2	IO_L22P_2	F25		
2	IO_L24N_2	H22		
2	IO_L24P_2	H21		
2	IO_L25N_2	G23	NC	NC
2	IO_L25P_2	G24	NC	NC
2	IO_L43N_2	F26		
2	IO_L43P_2	G26		

FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch)



FG676 - 63/37 (Sn/Pb) Solder Balls
FGG676 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	$\sim$	2.25	2.60
A ₁	0.40	0.50	0.60
D/E	27.00 BSC		
D ₁ /E ₁	25.00 REF		
e	1.00 BSC		
øb	0.50	0.60	0.70
aaa	$\sim$	$\sim$	0.20
ccc	$\sim$	$\sim$	0.35
ddd	$\sim$	$\sim$	0.30
eee	$\sim$	$\sim$	0.10
M	26		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

676-BALL FINE PITCH BGA (FG676/FGG676)

Figure 4: FG676/FGG676 Fine-Pitch BGA Package Specifications

BG728/BGG728 Standard BGA Package

As shown in Table 10, XC2V3000 Virtex-II devices are available in the BG728/BGG728 BGA package. Following this table are the **BG728/BGG728 Standard BGA Package Specifications (1.27mm pitch)**.

Table 10: **BG728 BGA — XC2V3000**

Bank	Pin Description	Pin Number
0	IO_L01N_0	B3
0	IO_L01P_0	A3
0	IO_L02N_0	B4
0	IO_L02P_0	A4
0	IO_L03N_0/VRP_0	C5
0	IO_L03P_0/VRN_0	C6
0	IO_L04N_0/VREF_0	B5
0	IO_L04P_0	A5
0	IO_L05N_0	E6
0	IO_L05P_0	D6
0	IO_L06N_0	B6
0	IO_L06P_0	A6
0	IO_L19N_0	E7
0	IO_L19P_0	D8
0	IO_L21N_0	F8
0	IO_L21P_0/VREF_0	E8
0	IO_L22N_0	C7
0	IO_L22P_0	C8
0	IO_L24N_0	B7
0	IO_L24P_0	A7
0	IO_L25N_0	H9
0	IO_L25P_0	J9
0	IO_L27N_0	F9
0	IO_L27P_0/VREF_0	G9
0	IO_L28N_0	E9
0	IO_L28P_0	D9
0	IO_L30N_0	C9
0	IO_L30P_0	B9
0	IO_L49N_0	A8
0	IO_L49P_0	A9
0	IO_L51N_0	G10
0	IO_L51P_0/VREF_0	H10
0	IO_L52N_0	F10

Table 10: BG728 BGA — XC2V3000

Bank	Pin Description	Pin Number
4	IO_L94P_4	AE14
4	IO_L95N_4/GCLK3S	AF15
4	IO_L95P_4/GCLK2P	AG15
4	IO_L96N_4/GCLK1S	Y14
4	IO_L96P_4/GCLK0P	AA14
5	IO_L96N_5/GCLK7S	AC14
5	IO_L96P_5/GCLK6P	AB14
5	IO_L95N_5/GCLK5S	AG13
5	IO_L95P_5/GCLK4P	AF13
5	IO_L94N_5	AE13
5	IO_L94P_5/VREF_5	AD13
5	IO_L93N_5	AC13
5	IO_L93P_5	AB13
5	IO_L92N_5	AA13
5	IO_L92P_5	Y13
5	IO_L91N_5	W13
5	IO_L91P_5/VREF_5	W12
5	IO_L78N_5	AG12
5	IO_L78P_5	AF12
5	IO_L76N_5	AD12
5	IO_L76P_5	AC12
5	IO_L75N_5/VREF_5	AB12
5	IO_L75P_5	AB11
5	IO_L73N_5	Y12
5	IO_L73P_5	Y11
5	IO_L72N_5	AG11
5	IO_L72P_5	AF11
5	IO_L70N_5	AE11
5	IO_L70P_5	AD11
5	IO_L69N_5/VREF_5	AA10
5	IO_L69P_5	AA11
5	IO_L67N_5	AG10
5	IO_L67P_5	AF10
5	IO_L54N_5	AE10
5	IO_L54P_5	AD10

Table 10: BG728 BGA — XC2V3000

Bank	Pin Description	Pin Number
NA	VCCAUX	P26
NA	VCCAUX	P2
NA	VCCAUX	C26
NA	VCCAUX	C2
NA	VCCAUX	B14
NA	VCCINT	V18
NA	VCCINT	V14
NA	VCCINT	V10
NA	VCCINT	U17
NA	VCCINT	U16
NA	VCCINT	U15
NA	VCCINT	U14
NA	VCCINT	U13
NA	VCCINT	U12
NA	VCCINT	U11
NA	VCCINT	T17
NA	VCCINT	T11
NA	VCCINT	R17
NA	VCCINT	R11
NA	VCCINT	P18
NA	VCCINT	P17
NA	VCCINT	P11
NA	VCCINT	P10
NA	VCCINT	N17
NA	VCCINT	N11
NA	VCCINT	M17
NA	VCCINT	M11
NA	VCCINT	L17
NA	VCCINT	L16
NA	VCCINT	L15
NA	VCCINT	L14
NA	VCCINT	L13
NA	VCCINT	L12
NA	VCCINT	L11
NA	VCCINT	K18
NA	VCCINT	K14

Table 11: FF896 BGA — XC2V1000, XC2V1500, and XC2V2000

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
NA	VCCINT	N20		
NA	VCCINT	N11		
NA	VCCINT	M20		
NA	VCCINT	M11		
NA	VCCINT	L20		
NA	VCCINT	L19		
NA	VCCINT	L18		
NA	VCCINT	L17		
NA	VCCINT	L16		
NA	VCCINT	L15		
NA	VCCINT	L14		
NA	VCCINT	L13		
NA	VCCINT	L12		
NA	VCCINT	L11		
NA	VCCINT	K21		
NA	VCCINT	K10		
NA	VCCINT	J22		
NA	VCCINT	J9		
NA	GND	AK23		
NA	GND	AK8		
NA	GND	AJ29		
NA	GND	AJ2		
NA	GND	AH28		
NA	GND	AH21		
NA	GND	AH10		
NA	GND	AH3		
NA	GND	AG27		
NA	GND	AG4		
NA	GND	AF26		
NA	GND	AF19		
NA	GND	AF12		
NA	GND	AF5		
NA	GND	AE25		
NA	GND	AE6		
NA	GND	AD17		
NA	GND	AD14		
NA	GND	AC30		

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
3	IO_L53P_3	AD2	
3	IO_L52N_3	AC8	
3	IO_L52P_3	AB8	
3	IO_L51N_3/VREF_3	AB10	
3	IO_L51P_3	AC10	
3	IO_L50N_3	AD5	
3	IO_L50P_3	AE5	
3	IO_L49N_3	AE4	
3	IO_L49P_3	AF4	
3	IO_L48N_3	AB9	
3	IO_L48P_3	AC9	
3	IO_L47N_3	AE2	
3	IO_L47P_3	AF1	
3	IO_L46N_3	AD6	
3	IO_L46P_3	AE6	
3	IO_L45N_3/VREF_3	AD9	
3	IO_L45P_3	AE9	
3	IO_L44N_3	AF2	
3	IO_L44P_3	AG2	
3	IO_L43N_3	AF3	
3	IO_L43P_3	AG3	
3	IO_L30N_3	AD7	
3	IO_L30P_3	AE7	
3	IO_L29N_3	AF5	
3	IO_L29P_3	AG5	
3	IO_L28N_3	AE8	
3	IO_L28P_3	AD8	
3	IO_L27N_3/VREF_3	AF8	
3	IO_L27P_3	AF9	
3	IO_L26N_3	AH1	
3	IO_L26P_3	AJ1	
3	IO_L25N_3	AG4	
3	IO_L25P_3	AH5	
3	IO_L24N_3	AF6	
3	IO_L24P_3	AG6	
3	IO_L23N_3	AH3	

FF1517 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 13](#), XC2V4000, XC2V6000, and XC2V8000 Virtex-II devices are available in the FF1517 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for the pin differences in the XC2V4000 and XC2V6000 devices shown in the No Connect columns. Following this table are the [FF1517 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 13: FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
0	IO_L01N_0	B36		
0	IO_L01P_0	C36		
0	IO_L02N_0	J30		
0	IO_L02P_0	J29		
0	IO_L03N_0/VRP_0	D33		
0	IO_L03P_0/VRN_0	D34		
0	IO_L04N_0/VREF_0	C34		
0	IO_L04P_0	C35		
0	IO_L05N_0	H30		
0	IO_L05P_0	G30		
0	IO_L06N_0	D32		
0	IO_L06P_0	E33		
0	IO_L07N_0	A35	NC	
0	IO_L07P_0	A36	NC	
0	IO_L08N_0	K28	NC	
0	IO_L08P_0	J28	NC	
0	IO_L09N_0	E32	NC	
0	IO_L09P_0/VREF_0	F32	NC	
0	IO_L10N_0	B34	NC	
0	IO_L10P_0	B35	NC	
0	IO_L11N_0	H29	NC	
0	IO_L11P_0	H28	NC	
0	IO_L12N_0	F31	NC	
0	IO_L12P_0	G31	NC	
0	IO_L19N_0	C32		
0	IO_L19P_0	C33		
0	IO_L20N_0	M26		
0	IO_L20P_0	M25		
0	IO_L21N_0	E30		
0	IO_L21P_0/VREF_0	E31		
0	IO_L22N_0	A33		

Table 13: FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
NA	DONE	AP7		
NA	M0	AN32		
NA	M1	AP33		
NA	M2	AT35		
NA	HSWAP_EN	E34		
NA	TCK	G8		
NA	TDI	D35		
NA	TDO	E6		
NA	TMS	F7		
NA	PWRDWN_B	AN8		
NA	DXN	G32		
NA	DXP	F33		
NA	VBATT	D5		
NA	RSVD	H9		
NA	VCCAUX	AV20		
NA	VCCAUX	AT37		
NA	VCCAUX	AT3		
NA	VCCAUX	Y38		
NA	VCCAUX	Y2		
NA	VCCAUX	D37		
NA	VCCAUX	D3		
NA	VCCAUX	B20		
NA	VCCINT	AG27		
NA	VCCINT	AG20		
NA	VCCINT	AG13		
NA	VCCINT	AF26		
NA	VCCINT	AF20		
NA	VCCINT	AF14		
NA	VCCINT	AE25		
NA	VCCINT	AE24		
NA	VCCINT	AE23		
NA	VCCINT	AE22		
NA	VCCINT	AE21		
NA	VCCINT	AE20		
NA	VCCINT	AE19		

Table 14: BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000

Bank	Pin Description	Pin Number	No Connect in XC2V2000
3	IO_L03P_3	AD7	
3	IO_L02N_3/VRP_3	AE6	
3	IO_L02P_3/VRN_3	AF5	
3	IO_L01N_3	AH2	
3	IO_L01P_3	AH3	
4	IO_L01N_4/BUSY/DOUT ⁽¹⁾	AD9	
4	IO_L01P_4/INIT_B	AD10	
4	IO_L02N_4/D0/DIN ⁽¹⁾	AF7	
4	IO_L02P_4/D1	AG7	
4	IO_L03N_4/D2/ALT_VRP_4	AK3	
4	IO_L03P_4/D3/ALT_VRN_4	AJ5	
4	IO_L04N_4/VREF_4	AE8	
4	IO_L04P_4	AF8	
4	IO_L05N_4/VRP_4	AK4	
4	IO_L05P_4/VRN_4	AK5	
4	IO_L06N_4	AH6	
4	IO_L06P_4	AH7	
4	IO_L19N_4	AC10	
4	IO_L19P_4	AC11	
4	IO_L20N_4	AE9	
4	IO_L20P_4	AE10	
4	IO_L21N_4	AL4	
4	IO_L21P_4/VREF_4	AL5	
4	IO_L22N_4	AB12	
4	IO_L22P_4	AB13	
4	IO_L23N_4	AJ6	
4	IO_L23P_4	AJ8	
4	IO_L24N_4	AK6	
4	IO_L24P_4	AK7	
4	IO_L25N_4	AG8	NC
4	IO_L25P_4	AG9	NC
4	IO_L26N_4	AF9	NC
4	IO_L26P_4	AF11	NC
4	IO_L27N_4	AH8	NC
4	IO_L27P_4/VREF_4	AH9	NC
4	IO_L28N_4	AD11	NC
4	IO_L28P_4	AD12	NC

Table 14: BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000

Bank	Pin Description	Pin Number	No Connect in XC2V2000
5	IO_L24P_5	AG23	
5	IO_L23N_5	AE22	
5	IO_L23P_5	AE23	
5	IO_L22N_5	AK25	
5	IO_L22P_5	AK26	
5	IO_L21N_5/VREF_5	AH25	
5	IO_L21P_5	AG25	
5	IO_L20N_5	AB21	
5	IO_L20P_5	AC22	
5	IO_L19N_5	AL27	
5	IO_L19P_5	AL28	
5	IO_L06N_5	AK27	
5	IO_L06P_5	AJ27	
5	IO_L05N_5/VRP_5	AD23	
5	IO_L05P_5/VRN_5	AE24	
5	IO_L04N_5	AJ26	
5	IO_L04P_5/VREF_5	AH26	
5	IO_L03N_5/D4/ALT_VRP_5	AF23	
5	IO_L03P_5/D5/ALT_VRN_5	AF24	
5	IO_L02N_5/D6	AG24	
5	IO_L02P_5/D7	AF25	
5	IO_L01N_5/RDWR_B	AK28	
5	IO_L01P_5/CS_B	AK29	
6	IO_L01P_6	AF27	
6	IO_L01N_6	AF28	
6	IO_L02P_6/VRN_6	AE26	
6	IO_L02N_6/VRP_6	AE27	
6	IO_L03P_6	AH29	
6	IO_L03N_6/VREF_6	AH30	
6	IO_L04P_6	AB22	
6	IO_L04N_6	AB23	
6	IO_L05P_6	AG28	
6	IO_L05N_6	AG29	
6	IO_L06P_6	AH31	
6	IO_L06N_6	AG31	
6	IO_L19P_6	AA22	
6	IO_L19N_6	Y22	

Table 14: BF957 — XC2V2000, XC2V3000, XC2V4000, and XC2V6000

Bank	Pin Description	Pin Number	No Connect in XC2V2000
6	IO_L20P_6	AD25	
6	IO_L20N_6	AC24	
6	IO_L21P_6	AG30	
6	IO_L21N_6/VREF_6	AF30	
6	IO_L22P_6	AD26	
6	IO_L22N_6	AC26	
6	IO_L23P_6	AF29	
6	IO_L23N_6	AD29	
6	IO_L24P_6	AE28	
6	IO_L24N_6	AD28	
6	IO_L25P_6	AB24	NC
6	IO_L25N_6	AA24	NC
6	IO_L27P_6	AC25	NC
6	IO_L27N_6/VREF_6	AB25	NC
6	IO_L43P_6	AF31	
6	IO_L43N_6	AE31	
6	IO_L44P_6	AA23	
6	IO_L44N_6	Y23	
6	IO_L45P_6	AE30	
6	IO_L45N_6/VREF_6	AC30	
6	IO_L46P_6	AC28	
6	IO_L46N_6	AA28	
6	IO_L47P_6	AD27	
6	IO_L47N_6	AC27	
6	IO_L48P_6	AA25	
6	IO_L48N_6	Y25	
6	IO_L49P_6	AC29	
6	IO_L49N_6	AB29	
6	IO_L50P_6	AB27	
6	IO_L50N_6	AA27	
6	IO_L51P_6	AA26	
6	IO_L51N_6/VREF_6	Y26	
6	IO_L52P_6	AD31	
6	IO_L52N_6	AC31	
6	IO_L53P_6	W22	
6	IO_L53N_6	V22	
6	IO_L54P_6	Y27	
6	IO_L54N_6	W27	